



28th IEEE European Test Symposium

Venice, Italy - Hybrid Conference

May 22 - 26, 2023

cas.polito.it/ETS23

Call for Papers

The **IEEE European Test Symposium (ETS)** is Europe's premier forum dedicated to presenting and discussing scientific results, emerging ideas, hot topics, and new trends, industrial case-studies and applications, in the area of electronic-based circuits and system testing, reliability, safety, security and validation. The 2022 edition of ETS will be a hybride one.

ETS'23 is organized jointly by CNRS-INL and Politecnico di Torino, which co-sponsor the event together with the IEEE Council on Electronic Design Automation (CEDA). ETS'23 is technically sponsored by the IEEE Computer Society – Test Technology Technical Council (TTTC).

The program includes keynotes, scientific paper presentations, panels, tutorials, fringe workshops and highlights/demos from industry. Linked to the main ETS'23 symposium, the Test Spring School will be organized.

You are invited to participate and submit your contributions to ETS'23. The areas of interest include (but are not limited to) the following topics:

- **Dependable AI and AI for Testing (Hot Topic)**
- **Functional Safety and Reliability in Automotive (Hot Topic)**
- **Emerging technologies and architectures (Hot Topic)**
- **Security and Trust (Hot Topic)**
- **Analog, Mixed-Signal, RF**
- **DfT and Test Access Standards**
- **Validation, Verification Debug and Diagnosis**
- **Test generation, Fault Simulation, Fault Tolerance, Application and evaluation**

Submissions: ETS'23 seeks original, unpublished contributions of the following types:

- **Scientific Papers**, up to 6 pages, for inclusion in the Formal IEEE Proceedings
- **Industrial Papers**, up to 6 pages, for inclusion in the Informal Digest of Papers
- **Fringe Workshops proposals** about relevant and timely topics.

Key dates:

Title and abstract (Scientific papers)	December 9th, 2022
Full Scientific papers	December 16th, 2022
Notification of acceptance	February 6th, 2023
Camera-ready and manuscript registration	February 22th, 2023

Additional information: ETS'23 will produce Formal Proceedings of accepted scientific papers with ISBN number that will be included in the IEEE Xplore Digital Library. An Informal digest will be produced to include Industrial papers.

General Chairs

Paolo Bernardi, Politecnico di Torino, IT
paolo.bernardi@polito.it

Daniel Tille, Infineon, DE
daniel.tille@infineon.com

Program Chair

Alberto Bosio, Ecole Centrale de Lyon, INL, FR
alberto.bosio@ec-lyon.fr



IEEE

CEDA
IEEE Council on Electronic Design Automation



**IEEE
COMPUTER
SOCIETY**

tttc

General Chairs:

Paolo Bernardi, Politecnico di Torino, IT
Daniel Tille, Infineon, DE

General Vice-Chair:

Mottaqiallah Taouil, TU Delft, NL

Program Chair:

Alberto Bosio, Ecole Centrale de Lyon, FR

Program Vice-Chair:

Maria Michel, Cyprus University, CY

Finance Chair:

Bastien Deveautour, INL, FR

Topic Chairs:

Giulio Gambardella, Synopsys, IE
Haralampos Stratigopoulos, Sorbonne University, FR
Jyotika Athavale, NVIDIA, US
Riccardo Cantoro, Politecnico di Torino, IT
Ioana Vatajelu, Grenoble-Alpes University, FR
Marco Ottavi, Roma2 University, IT and UTwente, NL
Ilia Polian, Stuttgart University, DE
Johanna Sepulveda, Airbus, DE
Florence Azais, LIRMM, FR
Gildas Leger, CISC-Universidad de Sevilla, ES
Jennifer Dworak, Lyle School of Engineering, US
Rene Krenz-Baath, Hamm-Lippstadt University, DE
Graziano Pravadelli, Verona University, IT
Melania Schillinsky, NXP, DE
Fernanda Lima, UFRGS, BR
Stephan Eggersgluess, Siemens-Mentor, DE

Special Track Chairs:

Frank K. Gurkaynak, ETH Zurich, CH
Selma Saidi, TU Dortmund University, DE

Fringe Workshops Co-Chairs:

Alessandro Savino, Politecnico di Torino, IT
Yangling Li, Chicago University, US

Publicity Co-Chairs:

Alexandra Kourfali, ITI Stuttgart, DE
Giorgio Natale, TIMA, FR

Regional Liaison Co-Chairs:

Sule Ozev, Arizona State University, USA
Ernesto Sanchez, Politecnico di Torino, IT

Student Activities Co-Chairs:

Maria Michel, Cyprus University, CY
Maksim Jenihhin, Taltech, EE

Industry Link Co-Chairs:

Davide Appello, STMicroelectronics, IT
Souhir Mhira, Dolphin Design, FR

Awards Co-Chairs:

Liviu Miclea, CLUJ-NAPOCA University, RO
Sybille Hellebrand, Paderborn University, DE

PhD Contest Co-Chairs:

Anne Meixner, ENG.DAUGHTER, US
Arnaud Virazel, LIRMM, FR

PhD Forum Co-Chairs:

Paolo Rech, Trento University, IT
Angeliki Kritikakou, Rennes University, FR

Publication Co-Chairs:

Mottaqiallah Taouil, TU Delft, NL
Tara Ghasempuori, Taltech, EE

Virtualization Co-Chairs:

Stefano Di Carlo, Politecnico di Torino, IT
Tommaso Foscale, Politecnico di Torino, IT

Web Resource Co-Chairs:

Giusy Iaria, Politecnico di Torino, IT
Sebastian Huhn, University of Bremen, DE
Nicolò Bellarmino, Politecnico di Torino, IT
Andrea Calabrese, Politecnico di Torino, IT
Gabriele Filippini, Politecnico di Torino, IT
Francesco Angione, Politecnico di Torino, IT